

Level 3 Interconnect: Board-to-Board Interposers Flex-to-Board Interposers

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Product Overview

OVERVIEW:

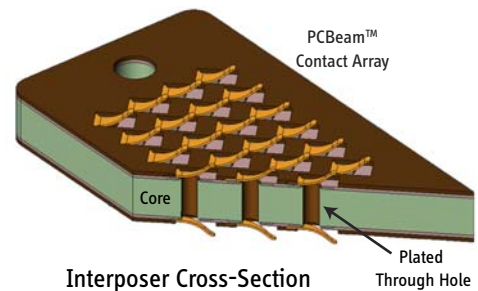
Neoconix's board-to-board and flex-to-board interposer products combine the flexibility of printed circuit (PCB) processing with the inherent reliability and performance of an all-metal electrical interconnect. PCBeam™ interposers can be used in a variety of board-to-board and flex-to-board applications in computing, military, medical, automated test, and mobile markets.

FEATURES:

- Continuous metal electrical path
- High Working Range (6-8 mils per side typical)
- Durability up to 10,000 cycles
- Mechanical wipe at interface
- Contacts integrated into substrate (no loose pieces)
- Circuitization/trace-routing possible within interposer substrate
- Wide range of thicknesses, contact counts, and configurations
- "Single-beam" or "dual-beam" options available
- Quick-turn prototypes
- No molds required
- Standard grids generally require no prototype tooling

SPECIFICATIONS (Typical*):

Pitch (standard)	0.8, 1.0, 1.1, 1.27 mm
Contact Count	various (10 to > 3,000 typ)
Compressed Thickness	various (0.8 mm - 3 mm typ)
Target Load/Contact	30 - 50 g standard
Working Range per Contact	12 mils (combined top + bottom)
Average Resistance	< 20 mΩ per position
Insulation Resistance	> 1 GΩ
Self Inductance	0.9 nH
Contact Wipe at Interface	Yes
Contact Plating	hard Au over Ni



Interposer Cross-Section



Typical Interposer

PCBeam™ Connector Technology
(single-beam shown)